



Maximum Performance – Silicone Gap Filler from RAMPF!

RAKU® SIL Gap Fillers maximize the service life of sensitive components by protecting these from overheating. Due to the high thermal conductivity our high performance two-component thermal interface materials ensure efficient heat dissipation while maintaining a low mechanical load.



Advantages

- High thermal conductivity
- Low density
- Minimal sedimentation
- Low SVHC content
- Excellent processing properties
- High thermal resistance



Typical applications

Power electronics, automotive electronic components, computers and peripherals, application between heat generating semiconductor devices and heat sinks.

Characteristics	Unit	RAKU® SIL 27-1217	RAKU® SIL 27-1222	RAKU® SIL 27-1230-2
Color		Blau	Blau	Blau
Viscosity A-Component at 20 °C	mPa·s	140,000	300,000	120,000
Viscosity B-Component at 20 °C	mPa·s	130,000	300,000	150,000
Doubling of mixture viscosity at 20°C	mPa·s	140,000	300,000	140,000
Mixing ratio A : B	Gew. TI	100 : 100	100 : 100	100 : 100
Pot life	min	28	20	7
Density	g/mL	1.90	2.00	2.5
Hardness	Shore 00	67	72	67
Operating temperature	°C	-40 bis +200	-40 bis +200	-40 bis +200
SVHC content	ppm	< 100	< 100	< 100
Thermal conductivity	W/m·K	1.7	2.2	3.0

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